Lab session on pixel front-end characterization

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4th International Summer School on

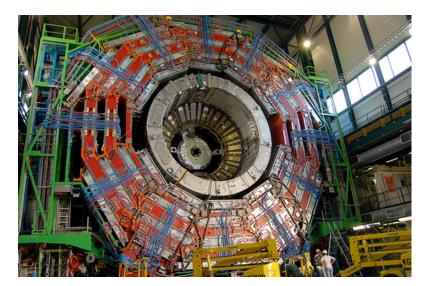
Intelligent Front-End Signal Processing for Frontier Exploitation in Research and Industry

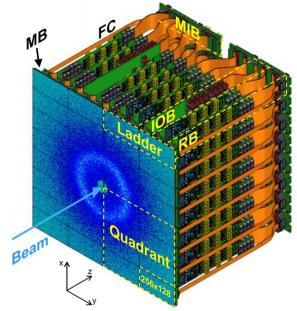
Sao Paulo, Brazil, 23 January - 3 February 2017



Focus of the lab

- Pixel front-end ASICs are located at the very beginning of the signal processing chain in pixel based detectors used in many fundamental and applied research fields
- Experimental characterization of front-end circuits in advanced microelectronic technologies is an integral part of the implementation of modern radiation detection systems
- The focus of the lab will be the characterization of a front-end channel for pixel detectors in a 65 nm CMOS technology
- The circuit under test was developed for the upgrade of the innermost layer of the CMS pixel detector to be deployed at the future High Luminosity Large Hadron Collider (HL-LHC)

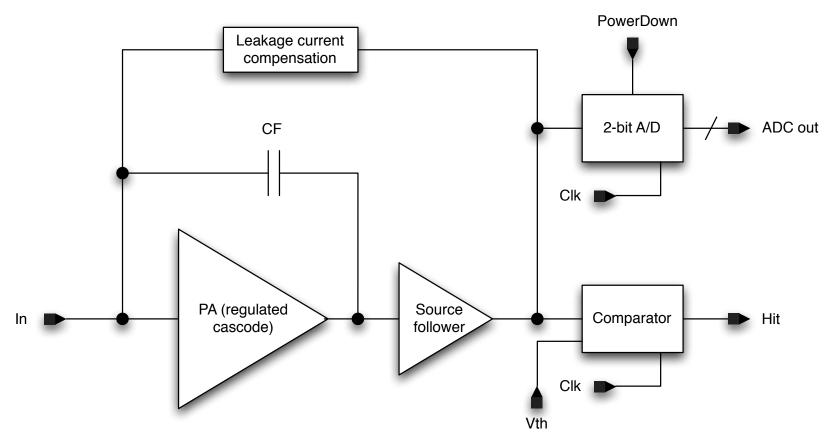




Pixel front-end specs for HL-LHC

- In the phase 2 upgrade of the ATLAS and CMS experiments at the LHC, the inner layers of the pixel trackers will have to face some serious challenges
 - very high hit rates: 1 2 GHz/cm² → need of intelligent pixel level data processing
 - very high radiation levels: 1 Grad total ionizing dose, 10¹⁶ neutrons/cm² fluence
 - very high trigger rates: 1 MHz
 - small pixel cells: $50x50 \text{ um}^2$ (or $25x100 \text{ um}^2$) \rightarrow improve resolution and reduce occupancy
 - small power dissipation: ~10 uW per cell (including analog and digital sections)
- Optimum front-end design requires a trade-off between noise, area, speed, power dissipation, amount of in-pixel functions
- The 65 nm CMOS process in its low power (LP) flavor is optimized for a reduced leakage and a small power consumption (at the price of a lower speed)

iFCP65 Front-end channel

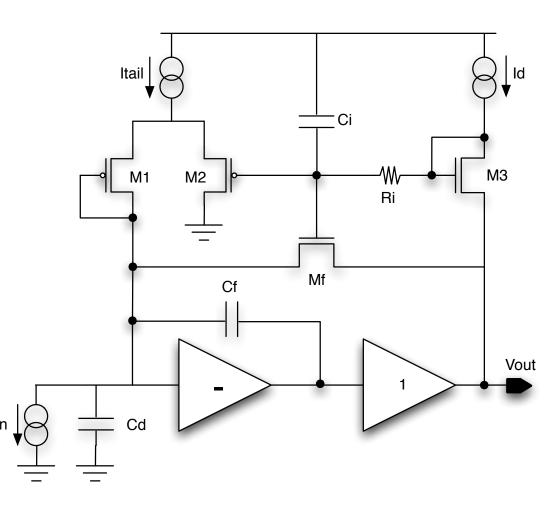


- Readout channel implementing a zero dead-time design hit detection takes no more than 25 ns
- Leakage current compensation up to 10 nA
- Hit comparator based on "praying mantis" architecture 12.5 ns reset phase + 12.5 ns comparison phase
- 2-bit flash ADC (3 discriminators, same as the hit comparator) for amplitude measurements

Charge preamplifier

- Regulated cascode design
- Active feedback transistor Mf:
 - 1/gm resistor for small signals
 - Constant current source for large signals
 - M1 provides a DC path for the detector leakage current
 - Ri + Ci ensures low frequency operation of the leakage compensation circuit
 - Itail > sum of expected detector leakage and k Id (k = mirror factor between M3 and Mf) $_{\delta Qin}$

• Current consumption $\sim 4.0 \, \mu A$



Chip layout

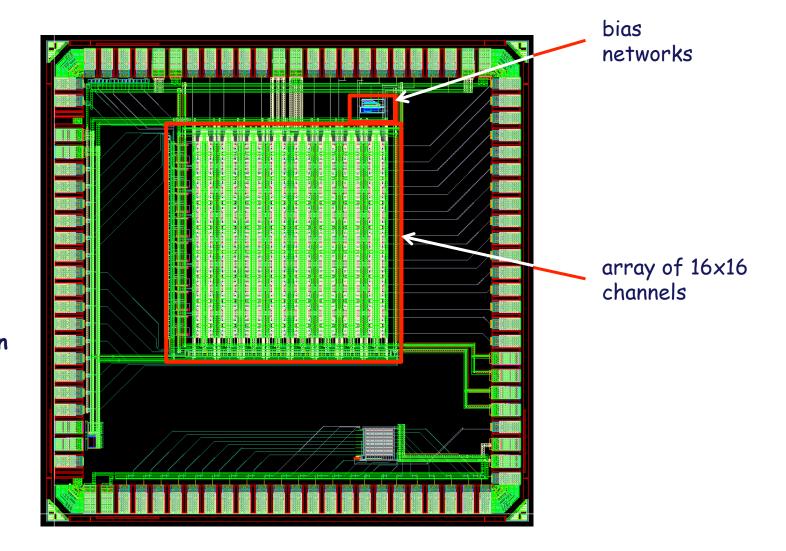
Chip developed by:
Davide Braga,
David Christian,
Grzegorz Deptuch,
Farah Fahim,
Luigi Gaioni,
Benedetta Nodari,
Lodovico Ratti,
Valerio Re,
Thomas Zimmermann

Design by:

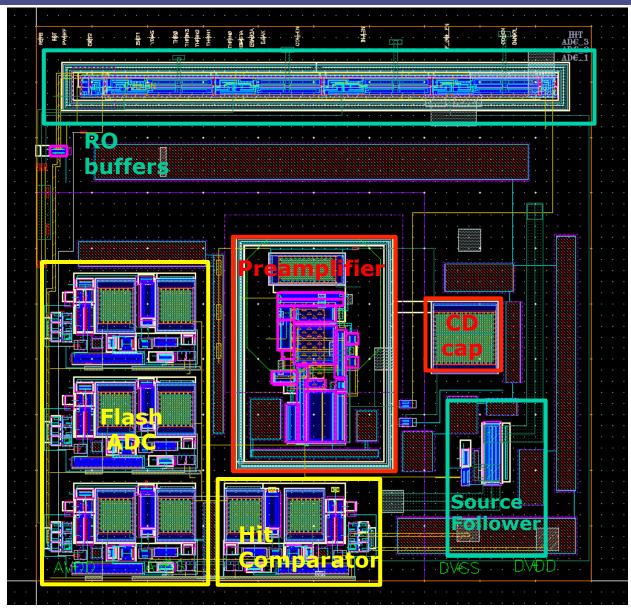
Davide Braga,

Luigi Gaioni,

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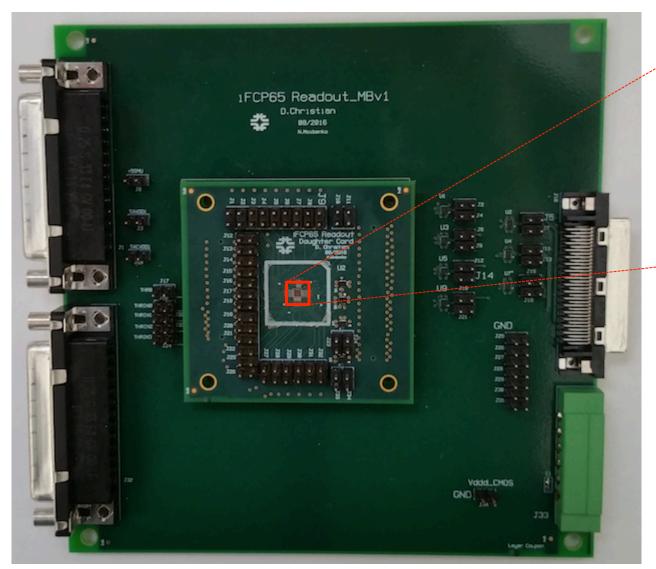


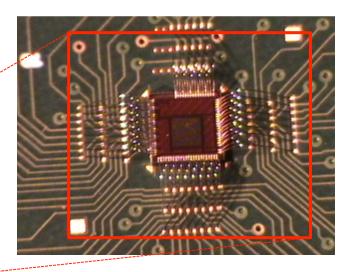
Front-end layout



- Front-end laid out in a 35um x 35um area
- RO buffers and source follower integrated in the top and right side of the pixel
- All the devices in the global P-substrate
- Nwell guard ring surrounding the preamplifier
- 35 fF detector emulating capacitance

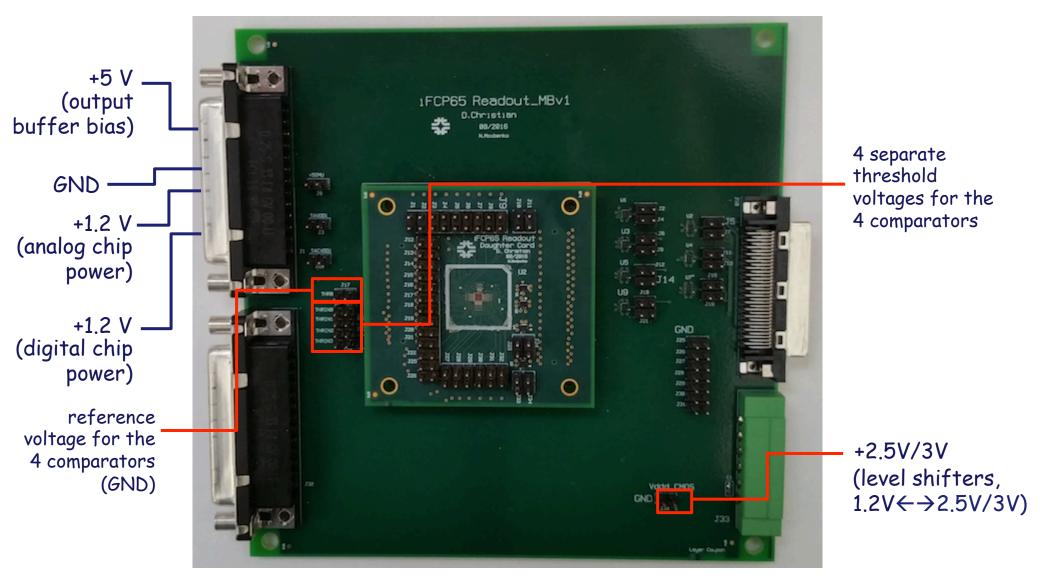
Test setup



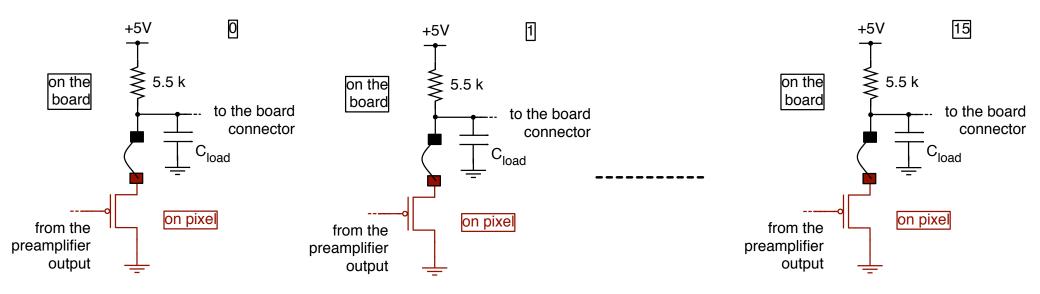


Chip on a small daughter board mounted on a test PCB, with connectors for power, bias, slow control (chip configuration), input and output (both digital and analog) signals

Power and reference voltages

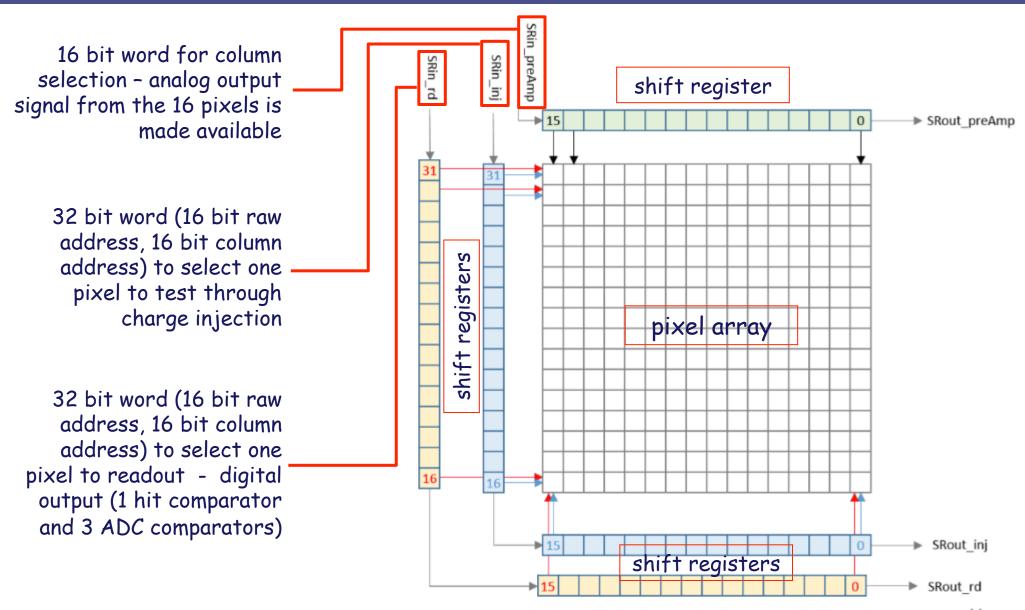


Output buffers

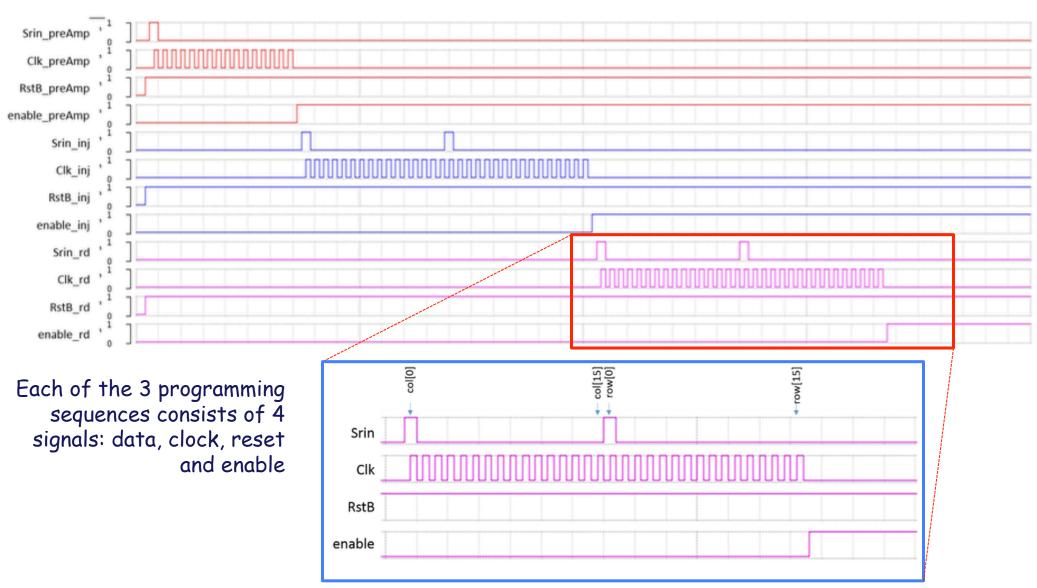


- 16 channels can be selected at a time the outputs of the relevant preamplifiers are available from test points on the daughter board (see next slides)
- Voltage buffers (PMOS source followers) available in each pixel to drive large loads (i.e., cables to the oscilloscope)
- +5V source used to bias the buffers
- Note that the output cap, on the rising edge of the signal, is charged through the 5.5k bias resistor e.g., if C_{load} =1 pF, τ =5 ns \rightarrow bandwidth limitation (low pass filtering) for the signal coming from the preamplifier \rightarrow low capacitance probe needed

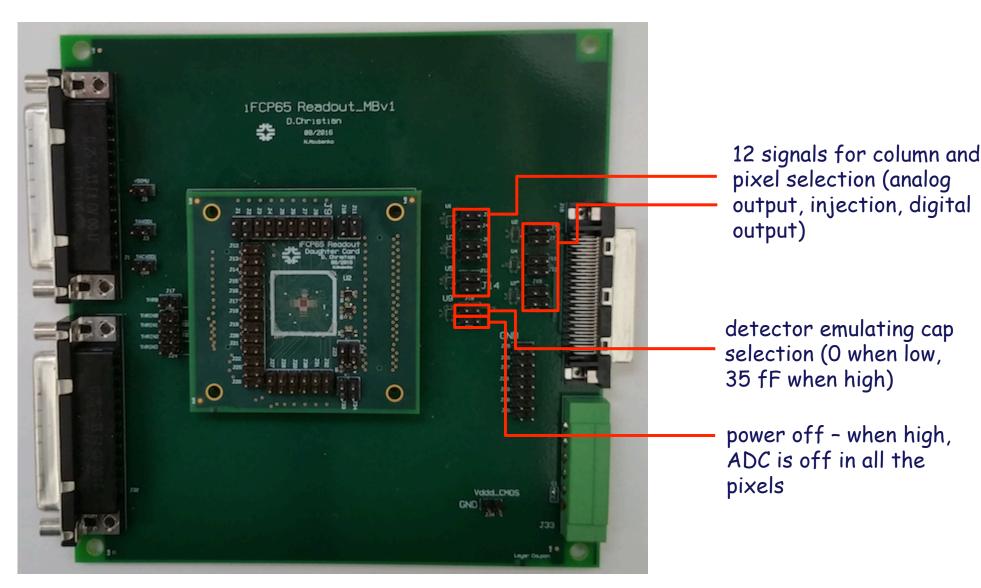
Chip configuration



Chip configuration: sample signals



Chip configuration



Inputs and outputs

analog output (16 test points, one for each pixel in the selected column) 1FCP65 Readout_MBv1

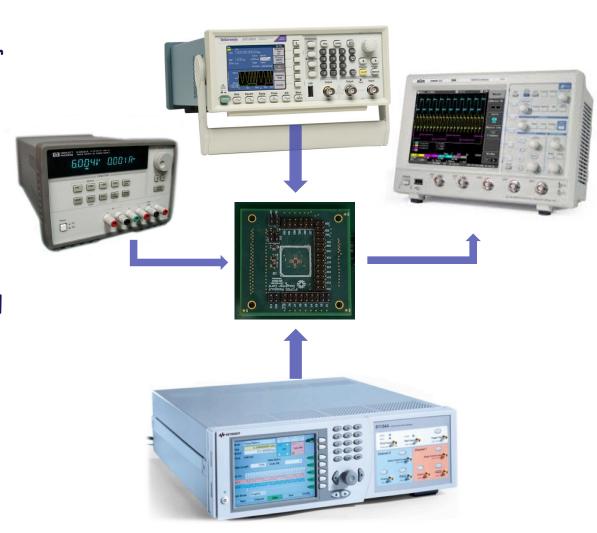
clock and complementary clock (for discriminator operation)

charge injection

comparator outputs (hit and ADC comparators)

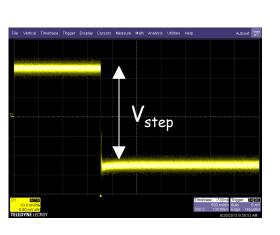
Instrumentation and prerequisites

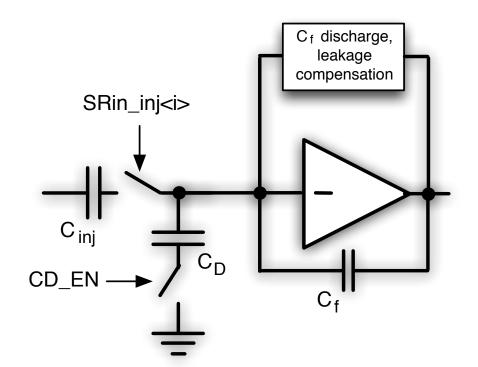
- Simple bench top instrumentation is required for measuring gain, ENC and response of the charge preamplifier and studying the behavior of the hit discriminator: power supply, digital scope, function generator, pattern generator
- No previous experience in pixel front-end characterization is required
- Basic knowledge on electronic circuit operation and standard electronic instrumentation can help

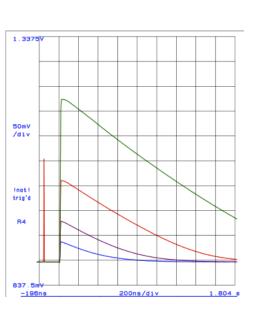


Signal at the preamplifier output

The expected signal at a charge preamplifier input is a current pulse - it can be obtained by differentiating a voltage step signal through the injection capacitance



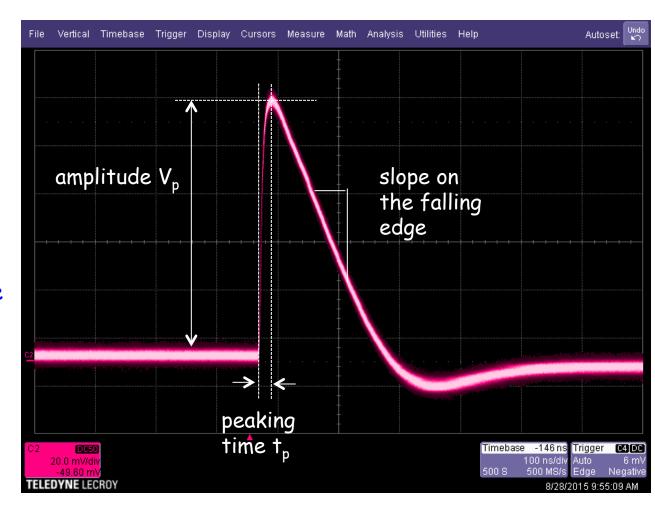




The actual input variable is the charge $Q=C_{inj}V_{step}$

Characterization of the preamplifier response

- Main signal parameters:
 - amplitude
 - peaking time (also as a function of the detector capacitance)
 - slope on the falling edge



Peaking time variation with C_D

The peaking time is found to increase with $C_{\rm D}$: to understand why assume a single pole approximation for the gain of the forward stage

$$A(s) = \frac{A_0}{1 + s\tau}$$

The closed loop gain is

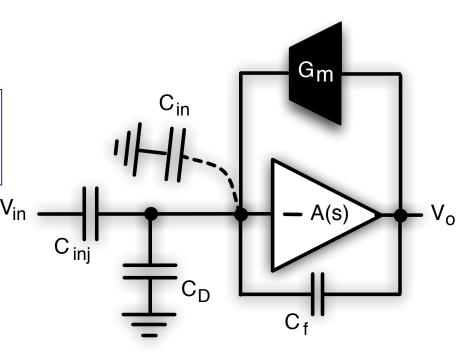
$$\frac{V_{o}}{V_{in}} \approx -\frac{2sC_{inj}}{G_{m}} \frac{1}{2s^{2}\tau^{C_{T}} A_{o}G_{m} + 2s^{(C_{T}} + A_{o}C_{f})} A_{o}G_{m} + 1$$

$$C_T = C_D + C_{in} + C_f + C_{inj}$$

In the high frequency regime, governing the response speed of the preamplifier

$$\frac{V_{o}}{V_{in}} \approx -\frac{C_{inj}}{C_{f}} \frac{1}{s_{\tau} C_{T} A_{o} C_{f}}$$

corresponding to an exponential response (of the 1-exp(-t/ τ_F) kind) with time constant



$$\tau_{\mathsf{F}} \approx \tau \frac{|\mathcal{C}_{\mathsf{D}}| + \mathcal{C}_{\mathsf{inj}} + \mathcal{C}_{\mathsf{f}} + \mathcal{C}_{\mathsf{in}}}{A_{\mathsf{O}} \mathcal{C}_{\mathsf{f}}}$$

Charge sensitivity

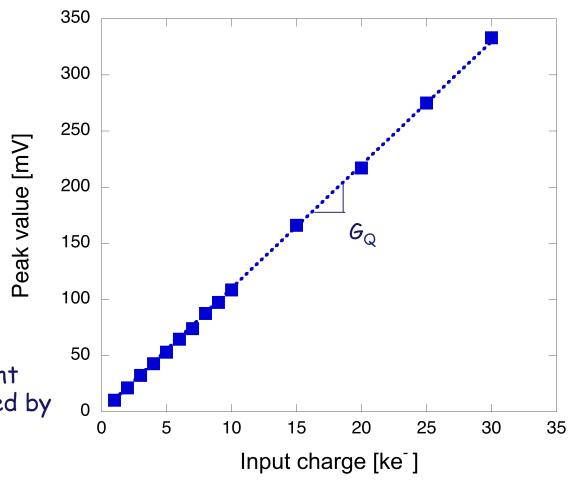
Is defined as

$$G_{Q} = \frac{dV_{p}}{dQ}$$

As long as the circuit is operated in the linear region

$$G_{\rm Q} = \frac{V_{\rm p}}{Q} \propto C_{\rm f}^{-1}$$

- To avoid the effects of local, slight non-linearities, G_Q can be measured by
 - measuring the amplitude for different values of the input charge
 - linearly interpolating the data points in the amplitude vs charge plot \Rightarrow $G_{\mathbb{Q}}$ is the slope of the interpolating straight line



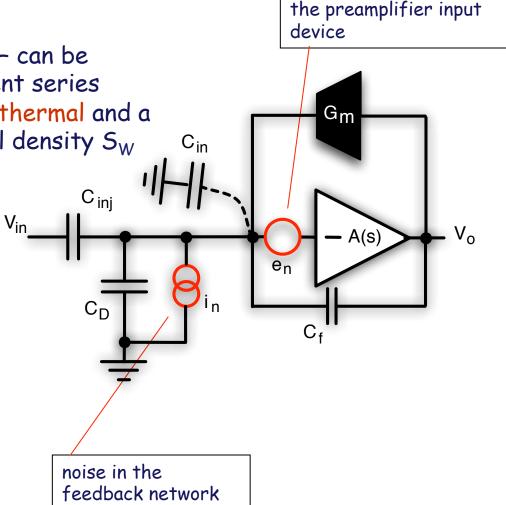
Noise and equivalent noise charge (ENC)

- The main noise sources in the preamplifier are located
 - in the preamplifier input device can be represented through an equivalent series source (e_n) and includes a white thermal and a flicker term with power spectral density S_W and S_f respectively

$$\frac{d\overline{e_n^2}}{df} = S_w + \frac{S_f}{f}$$

• in the feedback network - can be represented through an equivalent parallel source (i_n) , mostly with a white spectrum with power spectral density S_P

$$\frac{d\overline{i_n^2}}{df} = S_p$$



channel thermal and 1/f

noise contributions in

Noise and equivalent noise charge (ENC)

- Noise in the preamplifier is responsible for some degree of inaccuracy in the measurement of the signal amplitude at the circuit output
- Noise at the channel output can be measured as the standard deviation of the signal when no stimulus is applied to the input
- One can actually sample the voltage at the channel output and compute the standard deviation σ_n as

$$\sigma_{n} = \sqrt{\frac{1}{N} \sum_{i=1}^{N} x_{i}^{2} - \left(\frac{1}{N} \sum_{i=1}^{N} x_{i}\right)^{2}}$$

$$x_{i} = i - th sample$$

$$N = \# \text{ of samples}$$

which is easily done by using the statistical functions available in virtually all digital storage scopes

Noise and equivalent noise charge (ENC)

Equivalent noise charge is defined as the charge to be injected at the input to have an output signal with an amplitude $V_{\rm P}$ equal to the noise $\sigma_{\rm n}$, or the input charge needed to have a unit signal-to-noise-ratio at the output

$$\frac{G_{Q} \cdot ENC}{\sigma_{n}} = 1 \Rightarrow ENC = \frac{\sigma_{n}}{G_{Q}}$$

- So, to measure the ENC you need measure
 - the noise at the preamplifier output
 - · the charge sensitivity
- The ENC is a charge and is measured in Coulomb, but is seldom expressed in electrons

ENC[in electrons]=
$$\frac{ENC[Coulomb]}{1.602 \cdot 10^{-19} C}$$

ENC and detector capacitance

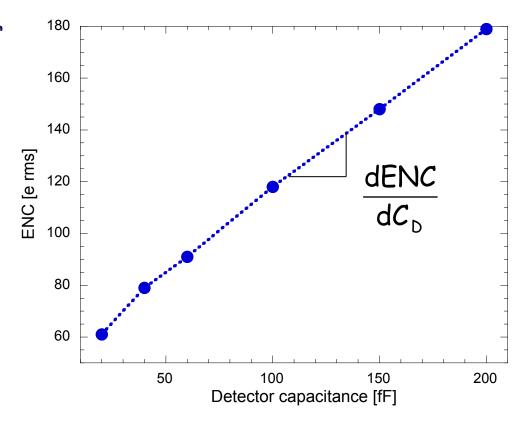
A quite general expression for the ENC is the following, accounting for the different noise contribution

$$ENC^2 = C_T^2 A_1 S_W \frac{1}{\tau} + C_T^2 A_2 S_f + A_3 S_p \tau$$

$$C_T = C_D + C_{in} + C_f + C_{inj}$$

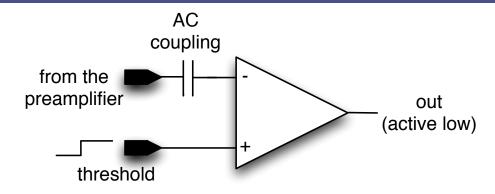
 A_1 , A_2 , $A_3 =$ shaping coefficient
 $\tau =$ shaping time (has some
relationship with t_p)

The effect of the series noise source on the overall noise performance gets more pronounced as C_T (the capacitance shunting the circuit input terminal) increases

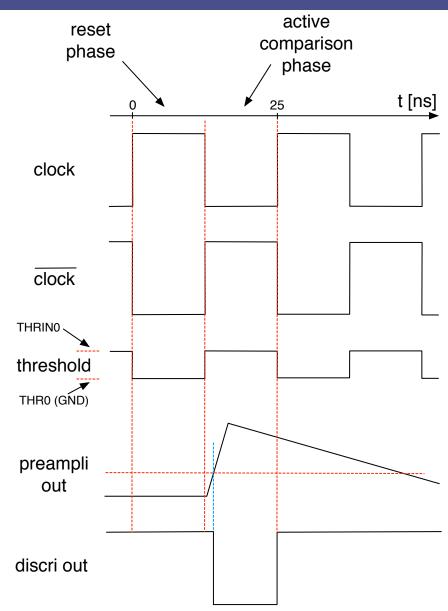


The slope of the ENC vs C_D is a figure of merit telling us how the noise performance of the circuit degrades as the detector capacitance increases

Discriminator operation



- Operation based on a reset and an active comparison phase
 - reset phase: comparator out (active low) is set to 1
 - comparison phase: preamplifier out is compared with a threshold
- AC coupling between preamplifier and discriminator → only positive changes in the preamplifier output signals are effective in triggering the discriminator
- Reset every 25 ns ensures zero dead time operation (25 ns is the bunch crossing period at the HL-LHC → potential detection of an event every 25 ns)



Discriminator architecture

